



AP1115AY15G, AP1115AY18G, AP1115AY25G, AP1115AY28G, AP1115AY30G, AP1115AY33G, AP1115AY35G, AP1115AY50G, AP1115BY15G, AP1115BY15G, AP1115BY25G, AP1115BY28G, AP1115BY30G, AP1115BY33G, AP1115BY35G, AP1115BY50G, AP1115BY3

Part Number: Analog SOT89-3L See List above p = package designator Weight (mg): 54.95 p = package designator See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)			ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	1.48	0.81	1000000	14767
Leadframe	CDA-194	Cu	7440-50-8	97.40%	44.35	24.37	974000	431991
		Fe	1309-37-1	2.40%			24000	10645
		Р	7723-14-0	0.08%			800	355
		Zn	7440-66-6	0.12%			1200	532
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.57	0.31	1000000	5702
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.22	0.12	1000000	2177
	EME-G600	Epoxy Resin		5.00%	51.15	28.11	50000	25577
Encapsulation		Phenol Resin		5.00%			50000	25577
		Bismuth/Bismuth compound		1.00%			10000	5115
		SiO2	60676-86-0	86.50%			865000	442484
		Cresol Novolac	29690-82-2	2.00%			20000	10231
		С	1333-86-4	0.50%			5000	2558
Die Attach Epoxy	84-3J	Epoxy Resin		47.50%	0.27	0.15	475000	1291
		Silicon dioxide		45.00%			450000	1223
		curing agent & hardener	Trade secret	7.50%			75000	204
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	1.96	1.08	1000000	19573
-	-	_		Total	100.00	54.95		1000000

Tolerance ±10%

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This product or product family does not contain any of the following substances except as CURRENTLY exempted by ELV II and RoHS and reported above:

Asbestos

Azo compounds

Cadmium and cadmium compounds Certain Shortchain Chlorinated Paraffins Chlorinated organic compounds

Hexavalent chromium compounds Lead and lead compounds

Mercury and mercury compounds Organic tin compounds Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)

Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) includin *DecaBDE*

Polychlorinated Biphenyls (PCBs)

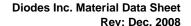
Polychlorinated Naphthalenes (> 3 chlorine atoms)

Radioactive Substances

Tributyl Tin (TBT) and Triphenyl Tin (TPT)

Tributyl Tin Oxide (TBTO)

^{*} The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables o EIA JIG-101, <u>Material Composition Declaration for Electronic Products</u>.





AP130-15YG-13, AP130-18YG-13, AP130-20YG-13, AP130-25YG-13, AP130-28YG-13, AP130-30YG-13, AP130-33YG-13, AP130-35YG-13, AP130-

Part Number: Analog SOT89-3L See List above p = package designator Weight (mg): 55.84 See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)			ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	4.51	2.52	1000000	45854
Leadframe		Cu	7440-50-8	97.40%	43.64	24.37	974000	431991
	CDA-194	Fe	1309-37-1	2.40%			24000	10645
	CDA-194	Р	7723-14-0	0.08%			800	355
		Zn	7440-66-6	0.12%			1200	532
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.56	0.31	1000000	5702
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.15	0.08	1000000	2177
		Epoxy Resin		5.00%	47.52	26.54	50000	25577
Encapsulation		Phenol Resin		5.00%			50000	25577
	EME-G600	Bismuth/Bismuth compound		1.00%			10000	5115
	EIVIE-GOOD	SiO2	60676-86-0	86.50%			865000	442484
		Cresol Novolac	29690-82-2	2.00%			20000	10231
		С	1333-86-4	0.50%			5000	2558
Die Attach Epoxy	8200TI	Ag	7440-22-4	80.00%	1.69	0.94	800000	2174
	620011	Acrylate resins	Trade secret	20.00%			200000	543
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	1.93	1.08	1000000	19260
•				Total	100.00	55.84		1030775

±10% Tolerance

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Asbestos Azo compounds

Organic tin compounds

Cadmium and cadmium compounds Certain Shortchain Chlorinated Paraffins Chlorinated organic compounds Hexavalent chromium compounds Lead and lead compounds Mercury and mercury compounds

Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.) Ozone Depleting Substances - Class II (HCFCs) Perfluorooctane Sulphonate (PFOS) or related compounds

Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) includin **DecaBDE**

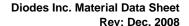
Polychlorinated Biphenyls (PCBs) Polychlorinated Naphthalenes (> 3 chlorine atoms)

Radioactive Substances

Tributyl Tin (TBT) and Triphenyl Tin (TPT)

Tributyl Tin Oxide (TBTO)

^{*} The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables o EIA JIG-101, Material Composition Declaration for Electronic Products.





AP1117YG-13, AP1117Y15G-13, AP1117Y18G-13, AP1117Y25G-13, AP1117Y33G-13, AP1117Y50G-13

Part Number: Analog SOT89-3L See List above p = package designator Weight (mg): 55.24 p = package designator See Data Sheet

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)		Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	1.47	0.81	1000000	14767
Leadframe		Cu	7440-50-8	97.40%	44.11	24.37	974000	431991
	CDA-194	Fe	1309-37-1	2.40%			24000	10645
	CDA-194	Р	7723-14-0	0.08%			800	355
		Zn	7440-66-6	0.12%			1200	532
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	0.57	0.31	1000000	5702
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.34	0.19	1000000	2177
		Epoxy Resin		5.00%	50.87	28.10	50000	25577
Encapsulation	EME-G600 -	Phenol Resin		5.00%			50000	25577
		Bismuth/Bismuth compound		1.00%			10000	5115
		SiO2	60676-86-0	86.50%			865000	442484
		Cresol Novolac	29690-82-2	2.00%			20000	10231
		С	1333-86-4	0.50%			5000	2558
Die Attach Epoxy	8200TI -	Ag	7440-22-4	80.00%	0.70	0.39	800000	2174
		Acrylate resins	Trade secret	20.00%			200000	543
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	1.95	1.08	1000000	19468
•				Total	100.00	55.24		999895

Tolerance ±10%

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Chlorinated organic compounds
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds

Organic tin compounds

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Ozone Depleting Substances - Class II (HCFCs)

Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) includin**DecaBDE**

Polychlorinated Biphenyls (PCBs)

Polychlorinated Naphthalenes (> 3 chlorine atoms)

Radioactive Substances

Tributyl Tin (TBT) and Triphenyl Tin (TPT)

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